# SN54LS373, SN54LS374, SN54S373, SN54S374, SN54S373, SN74LS374, SN74S373, SN74S374 SDLS165 OCTAL D-TYPE TRANSPARENT LATCHES AND EDGE-TRIGGERED FLIP-FLOPS

OCTOBER 1975-REVISED MARCH 1988

- Choice of 8 Latches or 8 D-Type Flip-Flops In a Single Package
- 3-State Bus-Driving Outputs
- Full Parallel-Access for Loading
- Buffered Control Inputs
- Clock/Enable Input Has Hysteresis to Improve Noise Rejection ('S373 and 'S374)
- P-N-P Inputs Reduce D-C Loading on Data Lines ('S373 and 'S374)

'LS373, 'S373 FUNCTION TABLE

OUTPUT ENABLE	ENABLE LATCH	D	OUTPUT
L	Н	Н	I
L /	_ н	L	L
L '	L	Х	$\alpha_0$
Н	x	×	Z

'LS374, 'S374 FUNCTION TABLE

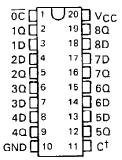
OUTPUT ENABLE	CLOCK	D	ОШТРИТ
L	<b>†</b>	Н	н
L	<b>†</b>	L	L
L	L	X	<u> </u>
Н _	Х	Х	Ż

#### description

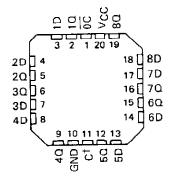
These 8-bit registers feature three-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. The high-impedance third state and increased high-logic-level drive provide these registers with the capability of being connected directly to and driving the bus lines in a bus-organized system without need for interface or pull-up components. They are particularly attractive for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'LS373 and 'S373 are transparent D-type latches meaning that while the enable (C) is high the Q outputs will follow the data (D) inputs. When the enable is taken low the output will be latched at the level of the data that was set up.

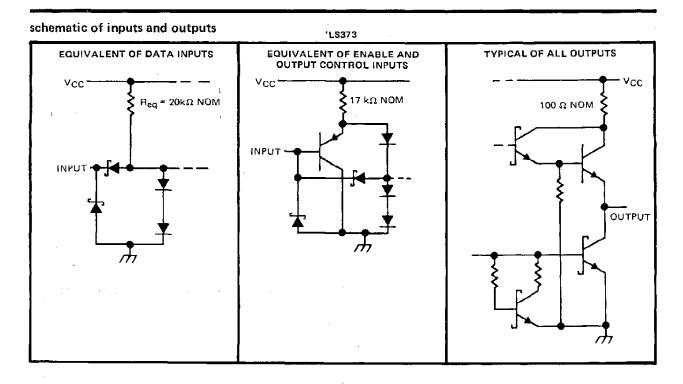
SN54LS373. SN54LS374. SN54S373. SN54S374...J OR W PACKAGE SN74LS373, SN74LS374, SN74S373. SN74S374...DW OR N PACKAGE (TOP VIEW)

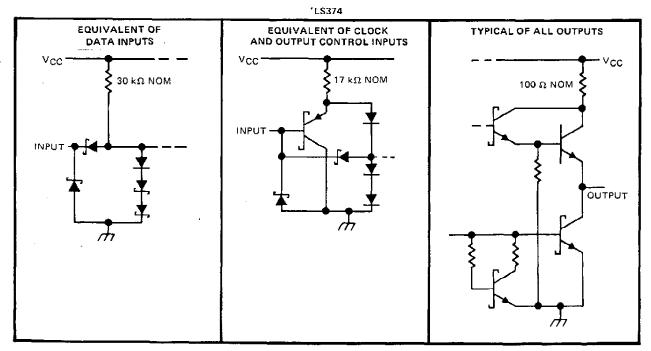


SN54LS373. SN54LS374, SN54S373. SN54S374 . . . FK PACKAGE (TOP VIEW)



<sup>1</sup>C for 'LS373 and 'S373; CLK for 'LS374 and 'S374.





# SN54LS373, SN54LS374, SN74LS373, SN74LS374 OCTAL D-TYPE TRANSPARENT LATCHES AND **EDGE-TRIGGERED FLIP-FLOPS**

absolute maximum ratings	over operating from	ee-air temperature	range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)				-				-								7 V
Input voltage																7 V
Off-state output voltage											-				5.	5 V
Operating free-air temperature ran	ige: S	N54LS	· .	-	,							_	55°	C to	12	5°C
		N74LS														
Storage temperature range																

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		<del></del>		SN54LS	<b>S</b> '		דומט		
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
۷он	High-level output voltage				5.5			5.5	V
Юн	High-level output current				- 1			- 2.6	mA
10 L	Low-level output current				12			24	_mA
tw -	Pulse duration	CLK high	15			15			ns
***		CLK low	15			15			[ ""
	Data setup time	'L\$373	5	Į.		5			
tsu	Data setup time	'L\$374	20	t		201			ns
	Data hold time	'LS373	20	ļ		201			<u> </u>
t <sub>h</sub>	Data noid time	'LS374†	5	†		01			ns
TA	Operating free-pir temperature		- 55		125	0		70	°c

<sup>&</sup>lt;sup>†</sup>The t<sub>h</sub> specification applies only for data frequency below 10 MHz. Designs above 10 MHz should use a minimum of 5 ns. (Commercial only)

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIO	NCT.	1	SN54LS	3"		SN74LS	i'	
	· Adding Len	TEST CONDITIO	M2.	MIN	TYP‡	МАХ	MIN	TYP‡	MAX	דומט
$v_{IH}$	High-level input voltage			2			2			٧
VIL	Low-level input voltage					0.7			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			· · · · · · · · · · · · · · · · · · ·	-1.5			1.5	V
voн	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = V <sub>IL</sub> max, I <sub>OH</sub> = MAX		2.4	3.4		2,4	3.1		V
Voi	Low-level putput voltage	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	.,
·UL	Low-rever burbat vortage	V <sub>fL</sub> = V <sub>fL</sub> max	IOL = 24 mA					0.35	0.5	V
10=11	Off-state output current,	V <sub>CC</sub> = MAX, V <sub>IH</sub> = 2 V,	- <del>1</del>	l —						
IOZH	high-level voltage applied	V <sub>O</sub> = 2.7 V				20			20	μΑ
Jozl	Off-state output current,	V <sub>CC</sub> = MAX, V <sub>IH</sub> = 2 V,								
'UZL	low-level voltage applied	V <sub>O</sub> ≈ 0.4 V				-20			-20	μΑ
tj	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V				0.1			0.1	mΑ
ΉΗ	High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.7 V				20			20	μΑ
HL	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V				-0.4			-0.4	mΑ
los	Short-circuit output current§	V <sub>CC</sub> = MAX		-30		-130	-30		-130	mΑ
lcc	Supply current	V <sub>CC</sub> = MAX,	'LS373		24	40		24	40	
'CC	Supply Cultent	Output control at 4,5 V	'LS374		27	40		27	40	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriats value specified under recommended operating conditions. ‡All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ} \text{ C}$ . § Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

# SN54LS373, SN54LS374, SN74LS373, SN74LS374 OCTAL D-TYPE TRANSPARENT LATCHES AND EDGE-TRIGGERED FLIP-FLOPS

# switching characteristics, VCC = 5 V, TA = 25°C

	FROM	TO			'LS373			UNIT		
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONL
fmax							35	50		MHz
<sup>t</sup> PLH	_		1		12	18				ns
†PHL	Data	Any Q			12	18				113
<sup>t</sup> PLH	Clock or		$C_L = 45 \text{ pF}, R_L = 667 \Omega$		20	30		15	28	
tPHL	enable	Any Q	See Notes 2 and 3		18	30		19	28	ns
<sup>t</sup> PZH	Output		-		15	28		20	26	ns
tPZL	Control	Any Q			25	36		21	28	11.5
	Output	2 0			15	25		15	28	ns
<sup>t</sup> PHZ	Control	Any Q	C <sub>L</sub> = 5 pF, H <sub>L</sub> = 567 17 See Note 3		13	23				
	Output				12	20		12	20	пs
<sup>†</sup> PLZ	Control	Any Q			12	20	l .			1,3

NOTES: 2. Maximum clock frequency is tested with all outputs loaded.

3. Load circuits and voltage waveforms are shown in Section 1.

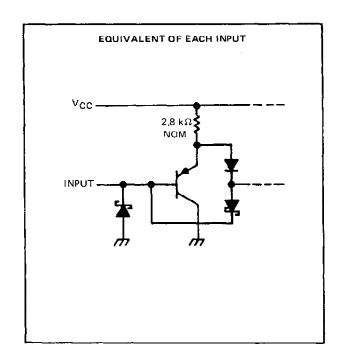
f<sub>max</sub> ≡ maximum clock frequency

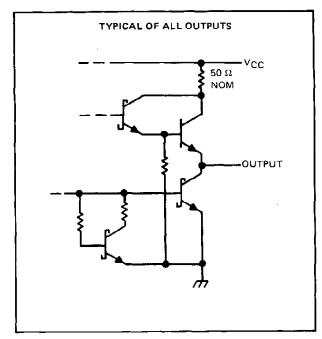
tpLH = propagation delay time, low-to-high-level output tpHL = propagation delay time, high-to-low-level output

tpZH = output enable time to high level
tpZL = output enable time to low level
tpHZ = output disable time from high level
tpLZ = output disable time from low level

# SN54S373, SN54S374, SN74S373, SN74S374 OCTAL D-TYPE TRANSPARENT LATCHES AND EDGE-TRIGGERED FLIP-FLOPS

#### schematic of inputs and outputs





## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see N	ote 1)																7 V
Input voltage																. 5	.5 V
Off-state output voltage									_							. 5	.5 V
Operating free-air temperat	ure range	: SN	154	S'											-55°	C to 12	25°C
		SN	174	S'				,							. 0	°C to 7	70°C
Storage temperature range										٠	٠				_65°	C to 15	so°C

## NOTE 1: Voltage values are with respect to network ground terminal,

# recommended operating conditions

			SN54S'					
	_	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	V
High-level output voltage, VOH				5.5			5.5	V
High-level output current, IOH				-2			6.5	mA
Width of clock/enable pulse, tw	High	6			6_			
— Clock/eliable bulse, IW	Low	7.3			7.3			ns
Data setup time, t <sub>su</sub>	'S373	01			O.			
——————————————————————————————————————	′5374	5↑			5↑			ns
Data hold time, th	<b>'S373</b>	101			10↓			
Data Hold (line, th	'5374	2†			2↑			ns
Operating free-air temperature, TA		~55	_	125	0	· ·	70	^c

# electrical characteristics over recommended operating free-air temperature range (unless otherwise

PARAMETER		TEST CO	ONDITIONS <sup>†</sup>		MIN	TYP‡	MAX	UNIT
V <sub>IH</sub>	<del></del>				2			V
VIL							0.8	<b>V</b>
V <sub>IK</sub>	V <sub>CC</sub> = MIN,	I <sub>1</sub> = -18 mA					- 1.2	V
VOH SN54S'	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,	10H = MAX	2.4	3.4		V
VOL	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> = 0.8 V,	I <sub>OL</sub> = 20 mA			0.5	V
<sup>l</sup> ozh	$V_{CC} = MAX$	V <sub>IH</sub> = 2 V,	$V_0 = 2.4 \text{ V}$				50	μΑ
lozi.	VCC = MAX,	V <sub>IH</sub> = 2 V.	V <sub>O</sub> = 0.5 V		-		- 50	μΑ
l	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V					1	mA
1H	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V					50	μА
IIL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.5 V					- 250	μΑ
los§	V <sub>CC</sub> = MAX				-40		- 100	mA
				outputs high			160	
ſ	[	'S373		outputs low			160	
				outputs disabled			190	
Icc	V <sub>CC</sub> = MAX			outputs high			110	mA
		'S374		outputs low			140	
		53/4		outputs disabled			160	
	1		CLK and OC a	at 4 V, D inputs at 0 V			180	

<sup>\*</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PARAMETER	FROM	то	TEST CONDITIONS	T	<b>S373</b>			'S374		UNIT
FARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII
fmax							75	100		MHz
<sup>t</sup> PLH	Data	Any Q			7	12				
<sup>†</sup> PHL	Vala	Anyu	C = 15 = 5 = 000 C		7	12				ns
tpLH	Clock or	22.10	$C_L = 15  \text{pF}, R_L = 280  \Omega,$ See Notes 2 and 4		7	14		8	15	
tPHL .	enable	Any Q	See Notes 2 and 4		12	18		11	17	ns
<sup>t</sup> PZH	Output	A O			8	15		8	15	T
†PZL	Control	Any Q			11	18		11	18	ns
tPHZ	Output	3	C <sub>L</sub> = 5 pF, R <sub>L</sub> = 280 Ω,		6	9		5	9	
<sup>TPLZ</sup>	Control	Any Q	See Note 3		8	12		7	12	hs

NOTES: 2. Maximum clock frequency is tested with all outputs loaded.

4. Load circuits and voltage waveforms are shown in Section 1.

f<sub>max</sub> = maximum clock frequency

tpLH = propagation delay time, low-to-high-level output

TPHL ≡ propagation delay time, high-to-low-level output

tpZH = output enable time to high level tpzL = output enable time to low level

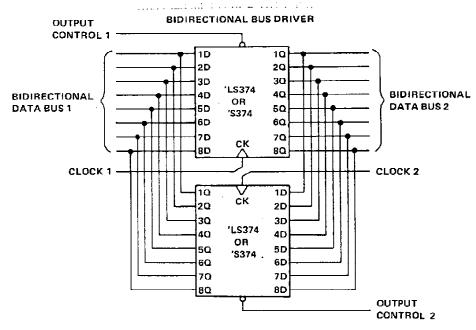
 $tpHZ \equiv output disable time from high level$ 

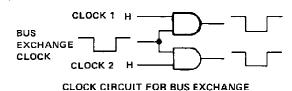
tpLz = output disable time from low level

 $<sup>^{\</sup>ddagger}$ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{A} = 25 ^{\circ}\text{C}$ .

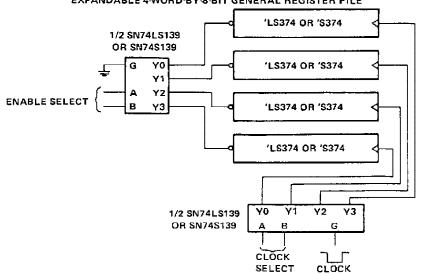
Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

#### TYPICAL APPLICATION DATA





## EXPANDABLE 4-WORD-BY-8-BIT GENERAL REGISTER FILE





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#### description (continued)

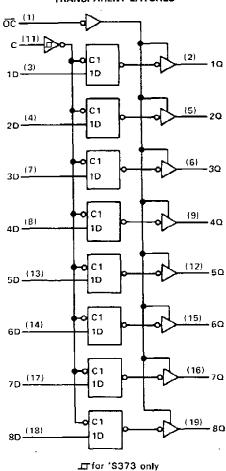
The eight flip-flops of the 'LS374 and 'S374 are edge-triggered D-type flip-flops. On the positive transition of the clock, the Q outputs will be set to the logic states that were setup at the D inputs.

Schmitt-trigger buffered inputs at the enable/clock lines of the 'S373 and 'S374 devices, simplify system design as ac and do noise rejection is improved by typically 400 mV due to the input hysteresis. A buffered output control input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state the outputs neither load nor drive the bus lines significantly.

The output control does not affect the internal operation of the latches or flip-flops. That is, the old data can be retained or new data can be entered even while the outputs are off.

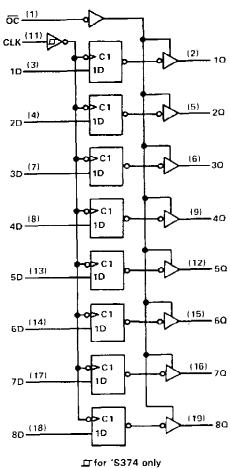
#### logic diagrams (positive logic)

'LS373, 'S373 TRANSPARENT LATCHES



Pin numbers shown are for DW, J, N, and W packages.

'LS374, 'S374 POSITIVE-EDGE-TRIGGERED FLIP-FLOPS



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